

BUFFING APPARATUS, AND SUBSTRATE PROCESSING APPARATUS

ABSTRACT OF THE DISCLOSURE

A buffing module for buffing a substrate is provided. The buffing module comprises a buff table for supporting the substrate, the buff table being rotatable; and a buff head to which a buff pad is attached, being rotatable and movable in a direction of approaching the buff table and a direction of moving away from the buff table. The buff pad includes a first part and a second part arranged so as to surround the first part on an outer side of the first part, the first part and the second part have different characteristics from each other. Selected Drawings: FIG. 7